

Inline soldering system VADU 300 XL

Automated soldering with vacuum



Optional automation solution with view on the transfer of the carrier from the lifting station to the conveyor belt.

The soldering system VADU 300 XL is equipped with three separate process chambers with internal substrate handling and inline carrier transfer for highly efficient series production. The system enables void-free solder connections with preforms and/or pastes in a continuous process. The reproducibility of the soldering processes is guaranteed by permanent process control.

The VADU 300 XL can also be integrated in customer's automation processes. PINK develops solutions according to customer's requirements which range from the optimization of the carrier handling through surrounding transfer systems to link-up with pick-and-place machines and robot automation.

Technical data

Process area (W x D): 410 x 280 mm (e.g. 4 cards à 5 x 7")

Clearance height: max. 100 mm

Dimensions of the system (W x D x H): 2,340 x 1,760 x 1,800 mm

Power supply: 3 x 400 V, 50/60 Hz

Power input: 25 kVA

Weight: 2,000 kg (without pumping unit)

System features

- Void-free solder connections
- Soldering with preforms and/or pastes
- Individual soldering profiles
- Soldering temperatures up to 400 °C
- Controlled temperature gradients
- Short cycle times
- Separate soldering and cooling chamber
- Formic acid process
- Flux management
- Inert gas atmosphere
- Residual oxygen content < 5 ppm
- Reproducibility of the soldering results
- Traceability
- Permanent process control
- USB connection
- Ethernet interface
- Remote maintenance (VPN)
- SMEMA interface
- Low energy and media consumption
- Internationally patented system

Options

- Wafer up to 12"
- Induction heating
- High vacuum
- Handling/Transfer systems



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